



BOW Tacky Paste Fluxes

Product Description

- Touch-up and rework applications
- Attachment of BGA spheres
- Soldering Flip Chip components
- Package-on-Package (PoP) applications
- Wide reflow window
- Excellent wetting compatibility
- Compatible with most board finishes

Bow Tacky Paste Flux	Type	IPC Classification
NC-1125LF	No Clean – Lead Free	REL0
NC-1150LF	No Clean & Water Soluble – Lead Free	REL0
NC-1150	No Clean & Water Soluble	REL0
NC-1170	No Clean	REL0
NC-1115	No Clean	REL0
WS-1250	Water Soluble	REM0
WS-1250.4	Water Soluble	REM0
WS-1250.6	Water Soluble	REM0
WS-1250LF	Water Soluble	REM0
RMA-750	RMA	REM0
RMA-750LF	RMA – Lead Free	REM0
RA-560	RA	REH0

Available Packaging

The following packaging options are available for stencil printing and dispensing applications: 75 and 150 gram jars; 150 gram cartridges; 10 and 30cc syringes.

Stencil Life

- > 8 hrs. @ 20-50% RH & 22-28°C
- ≈ 4 hrs. @ 50-70% RH & 22-28°C

Stencil Cleaning

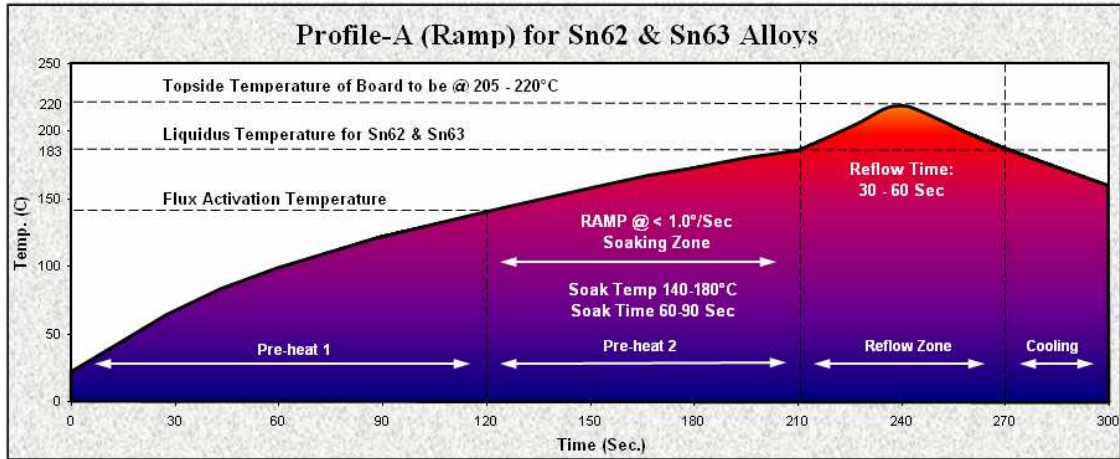
Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using IPA (isopropyl alcohol) is recommended.

Storage and Handling Procedures

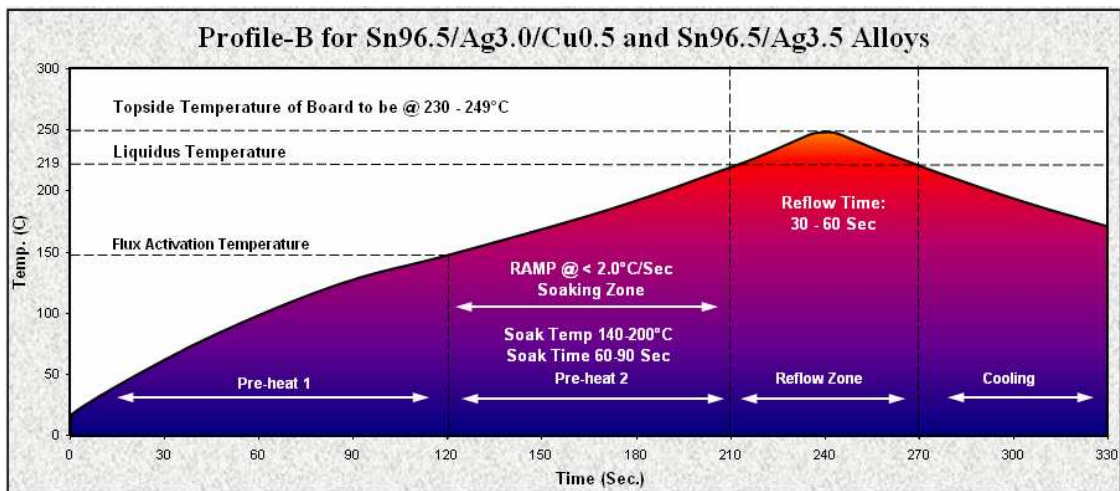
Refrigerated storage at 42-47° F will prolong the tacky paste flux's shelf life to no less than 1 year. Syringes & cartridges should be stored vertically with the dispensing tip down. Tacky paste flux should be allowed to reach ambient temperature naturally, prior to use (about 6-8 hours). NEVER FREEZE TACKY PASTE FLUX.

Recommended Profiles:

Profile-A was designed to serve as a starting position for process optimization using tacky paste fluxes. A cool down rate of (-) 2-4 C°/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components. This profile is recommended when soldering Sn62 or Sn63 alloys.



Profile-B was designed to serve as a starting position for process optimization using tacky paste fluxes. A cool down rate of (-) 2-4 C°/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components. This profile is recommended when soldering Sn96.5/Ag3.0/Cu.5 (SAC305) and Sn96.5/Ag3.5 alloys.



The information contained herein is based on data consideration to be accurate and is intended for use by persons having technical skills at their own discretion and risk. Since conditions of use are outside of Bow Electronics control, we cannot assume liability for results obtained or damage incurred due to misuse, nor can we assume customer liability.

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